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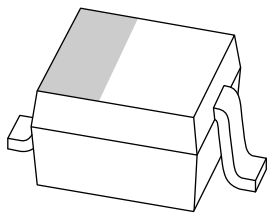
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DATA SHEET



BAP65-03 Silicon PIN diode

Product specification
Supersedes data of 2001 May 11

2004 Feb 11



Silicon PIN diode

BAP65-03

FEATURES

- High voltage, current controlled
- RF resistor for RF switches
- Low diode capacitance
- Low diode forward resistance (low loss)
- Very low series inductance.

APPLICATIONS

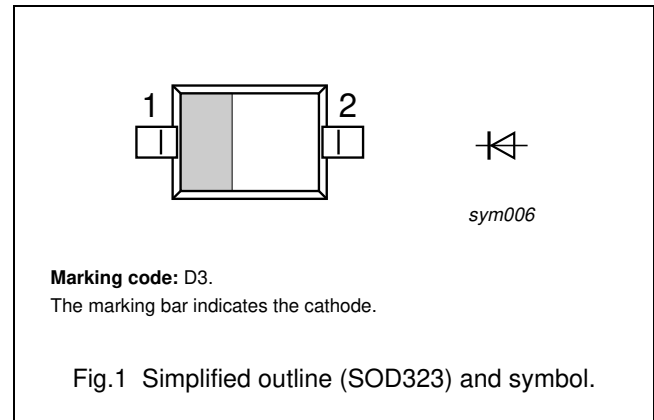
- RF attenuators and switches
- Bandswitch for TV tuners
- Series diode for mobile communication transmit/receive switch.

DESCRIPTION

Planar PIN diode in a SOD323 small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAP65-03	-	plastic surface mounted package; 2 leads	SOD323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		-	30	V
I_F	continuous forward current		-	100	mA
P_{tot}	total power dissipation	$T_s \leq 90\text{ }^\circ\text{C}$	-	500	mW
T_{stg}	storage temperature		-65	+150	$^\circ\text{C}$
T_j	junction temperature		-65	+150	$^\circ\text{C}$

Silicon PIN diode

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ELECTRICAL CHARACTERISTICST_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 50 mA	0.9	1.1	V
I _R	reverse leakage current	V _R = 20 V	–	20	nA
C _d	diode capacitance	V _R = 0 V; f = 1 MHz	0.65	–	pF
		V _R = 1 V; f = 1 MHz	0.55	0.9	pF
		V _R = 3 V; f = 1 MHz	0.5	0.8	pF
		V _R = 20 V; f = 1 MHz	0.375	–	pF
r _D	diode forward resistance	I _F = 1 mA; f = 100 MHz	1	–	Ω
		I _F = 5 mA; f = 100 MHz; note 1	0.65	0.95	Ω
		I _F = 10 mA; f = 100 MHz; note 1	0.56	0.9	Ω
		I _F = 100 mA; f = 100 MHz	0.35	–	Ω
s ₂₁ ²	isolation	V _R = 0; f = 900 MHz	10.2	–	dB
		V _R = 0; f = 1800 MHz	5.8	–	dB
		V _R = 0; f = 2450 MHz	4.1	–	dB
s ₂₁ ²	insertion loss	I _F = 1 mA; f = 900 MHz	0.1	–	dB
		I _F = 1 mA; f = 1800 MHz	0.14	–	dB
		I _F = 1 mA; f = 2450 MHz	0.18	–	dB
s ₂₁ ²	insertion loss	I _F = 5 mA; f = 900 MHz	0.06	–	dB
		I _F = 5 mA; f = 1800 MHz	0.1	–	dB
		I _F = 5 mA; f = 2450 MHz	0.14	–	dB
s ₂₁ ²	insertion loss	I _F = 10 mA; f = 900 MHz	0.06	–	dB
		I _F = 10 mA; f = 1800 MHz	0.1	–	dB
		I _F = 10 mA; f = 2450 MHz	0.13	–	dB
s ₂₁ ²	insertion loss	I _F = 100 mA; f = 900 MHz	0.05	–	dB
		I _F = 100 mA; f = 1800 MHz	0.1	–	dB
		I _F = 100 mA; f = 2450 MHz	0.14	–	dB
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	0.17	–	μs
L _S	series inductance	I _F = 100 mA; f = 100 MHz	1.5	–	nH

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

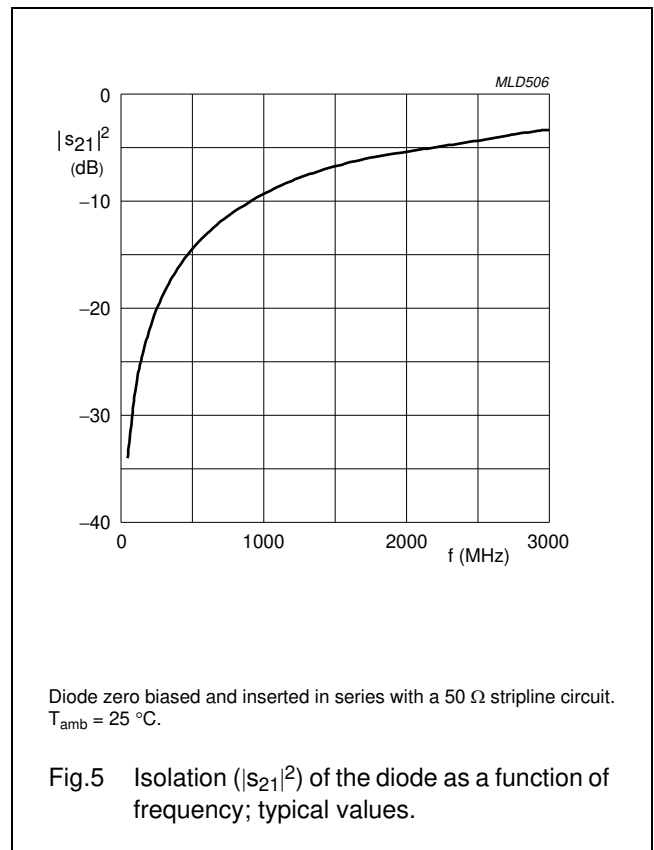
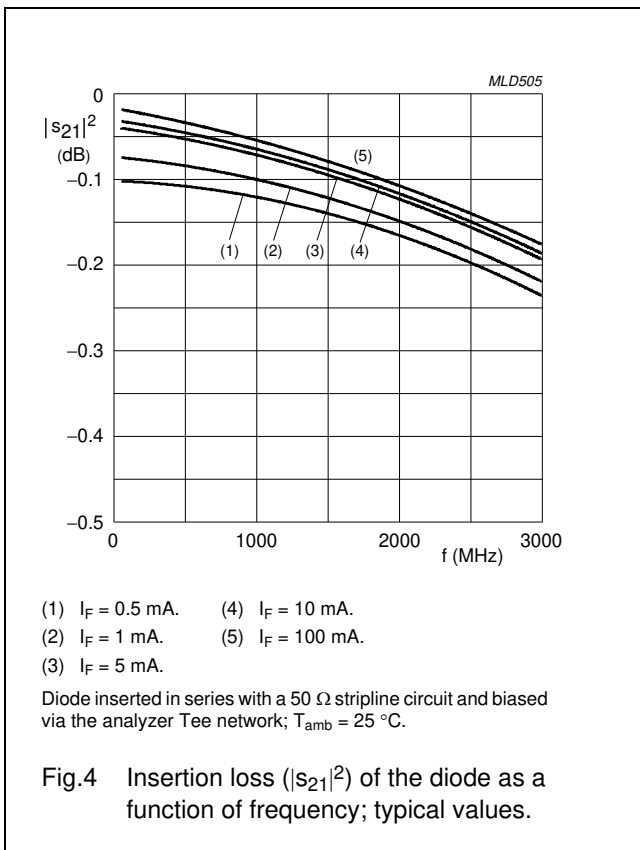
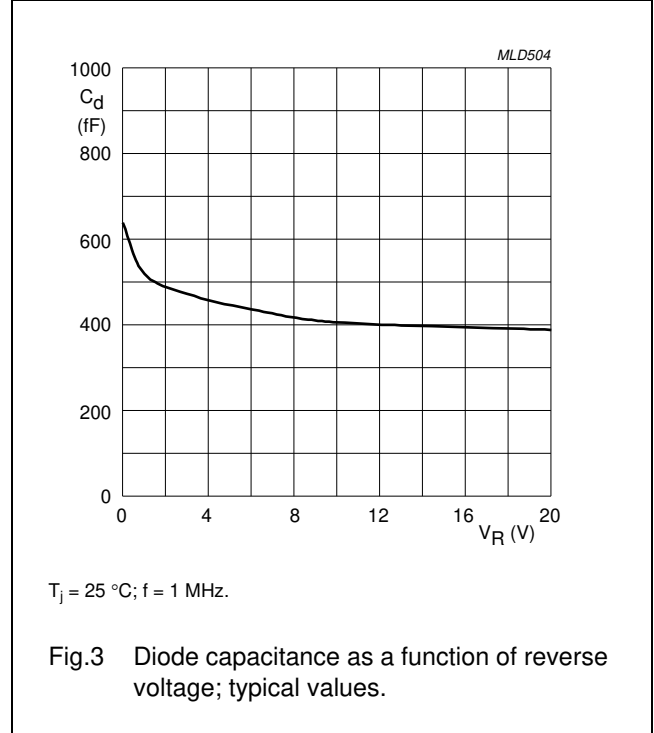
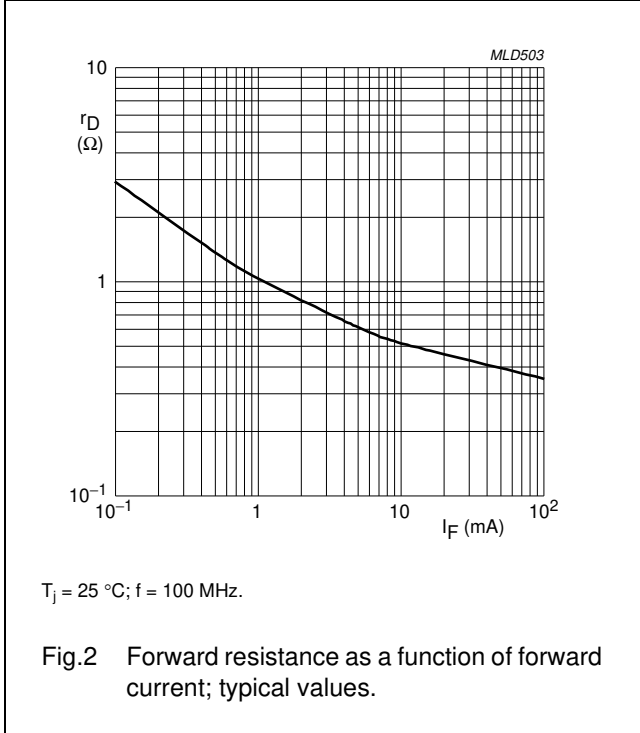
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th(j-s)}	thermal resistance from junction to soldering point	120	K/W

Silicon PIN diode

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GRAPHICAL DATA



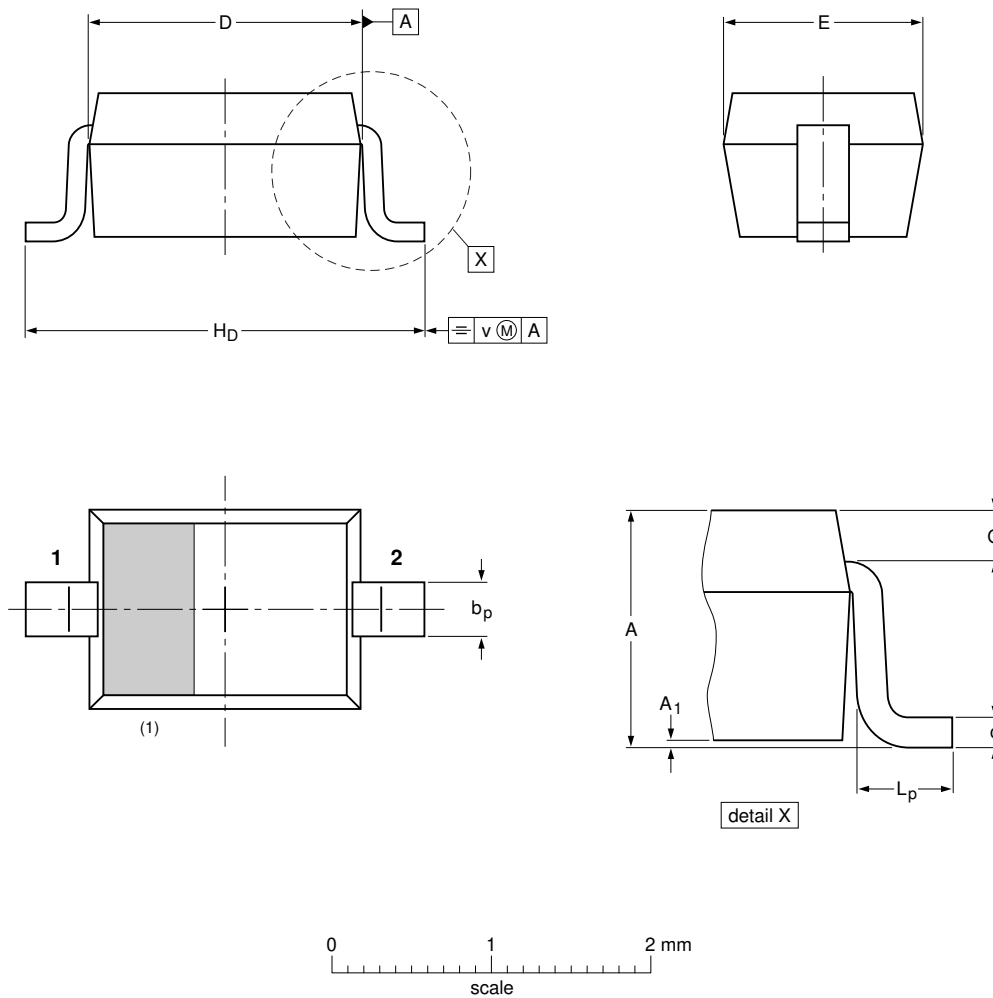
Silicon PIN diode

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PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A _{1 max}	b _p	c	D	E	H _D	L _p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		-03-12-17 06-03-16

Silicon PIN diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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Silicon PIN diode

BAP65-03

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: <http://www.nxp.com>

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